For Immediate Release

STATS ChipPAC Announces Resignation of Chief Financial Officer

Singapore – 28 March 2014 – STATS ChipPAC Ltd. ("STATS ChipPAC" or the "Company" – SGX-ST: STATSChP), a leading provider of advanced semiconductor packaging and test services, announced today that Mr. John Lau Tai Chong has resigned from his position as Senior Vice President and Chief Financial Officer with effect from 3 April 2014 to pursue other career opportunities.

"We thank John for his contributions to our finance and accounting function and wish him success in his future endeavors," said Mr. Tan Lay Koon, President and Chief Executive Officer, STATS ChipPAC.

The Company will announce in due course the replacement for the Chief Financial Officer position.

About STATS ChipPAC Ltd.

STATS ChipPAC Ltd. (SGX-ST Code: S24) is a leading service provider of semiconductor packaging design, assembly, test and distribution solutions in diverse end market applications including communications, digital consumer and computing. With global headquarters in Singapore, STATS ChipPAC has design, research and development, manufacturing or customer support offices throughout Asia, the United States and Europe. STATS ChipPAC is listed on the SGX-ST. Further information is available at www.statschippac.com. Information contained in this website does not constitute a part of this release.

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